FAIRCHILD
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PCN# : P251A
Issue Date : May. 24, 2012

DESIGN/PROCESS CHANGE NOTIFICATION

This is to inform you that a change is being made to the products listed below.

Unless otherwise indicated in the details of this notification, the identified change will have no impact on product quality, reliability, electrical, visual or mechanical performance and affected products will remain fully compliant to all published specifications. Products incorporating this change may be shipped interchangeably with existing unchanged products.

This change is planned to take effect in 90 calendar days from the date of this notification. Please work with your local Fairchild Sales Representative to manage your inventory of unchanged product if your evaluation of this change will require more than 90 calendar days.

Please contact your local Customer Quality Engineer within 30 days of receipt of this notification if you require any additional data or samples. Alternatively, you may send an email request for data, samples or other information to PCNSupport@fairchildsemi.com.

Implementation of change:

Expected First Shipment Date for Changed Product : Aug. 22, 2012

Expected First Date Code of Changed Product :1234

Description of Change (From) :
The products identified in the affected FSID list assembled at Fairchild Semiconductor in Suzhou, China (FSSZ).

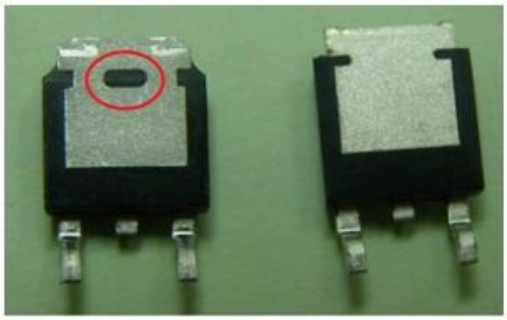
Description of Change (To) :
GEM Electronics Shanghai, China is qualified to produce the products identified in the affected FSID section on this PCN. GEM Electronics Shanghai, China has been a qualified assembly and test manufacturer for Fairchild since 2003.

BOM comparison between GEM and FSSZ:

Process/Material	GEM	FSSZ
Lead frame	Bare Cu	Bare Cu
Die attach material	Soft solder	Soft solder
Wire bonding material	Al wire	Al wire
Mold material	G631	EME6600CS

D-pak Package visual comparison as below:

GEM FSSZ



Note: There is a slot hole on GEM heat sink surface compared with Fairchild Suzhou (FSSZ) product. There is no impact to the application.

Reason for Change:
To have an alternate assembly and test site to increase manufacturing capacity.

Affected Product(s):

FJD3305H1TM	FJD5304DTF	FJD5553TM
FJD5555TM	KSC5402DTF	KSC5502DTM

Qualification Plan	Device	Package	Process	No. of Lots
Q20110166	FJD3305H1TM	DPAK	BJT	1

Test Description:	Condition:	Standard :	Duration:	Results:
MSL1 Precondition	260C, 3 cycles	JESD22-A113		0/154
High Temperature Reverse Bias Test	150°C Tj, 80% of Rated BV	JESD22-A108	1000 hrs	0/77
Temperature Cycle	-65C, 150C	JESD22-A104	500 cycles	0/77
Temperature Humidity Bias Test	85°C, 85% RH , 80% of Rated BV	JESD22-A101	1000 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Power Cycle	125°C TJC, delta Tj of 100 C, 2 min on, 2 min off	JESD22-A122	10k cycles	0/77

Qualification Plan	Device	Package	Process	No. of Lots
Q20110166	FJD5555TM	DPAK	BJT	1

Test Description:	Condition:	Standard :	Duration:	Results:
MSL1 Precondition	260C, 3 cycles	JESD22-A113		0/154
High Temperature Reverse Bias Test	150°C Tj, 80% of Rated BV	JESD22-A108	1000 hrs	0/77
Temperature Cycle	-65C, 150C	JESD22-A104	500 cycles	0/77
Temperature Humidity Bias Test	85°C, 85% RH , 80% of Rated BV	JESD22-A101	1000 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Power Cycle	125°C TJC, delta Tj of 100 C, 2 min on, 2 min off	JESD22-A122	10k cycles	0/77

Comment on Failure:

Other Qualification Data: